



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Seong Min Seo, Young Suk Chung, Jong Sik Paek, Jae Hun Ku, Jae Hak Yee

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package Including Stacked Chips

Serial No.: 09/816,599

Filing Date: March 23, 2001

Examiner: Not Yet Assigned

Group Art Unit: 2811

Docket No.: AB-1111 US

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Technology Center 2600

San Jose, California
February 19, 2002

BOX DAC
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

REQUEST FOR RECONSIDERATION OF PETITION UNDER 37 CFR 1.47(A)

Dear Sir:

A Decision Refusing Status Under 37 CFR 1.47(a) was mailed on December 26, 2001.

Subsequently, the inventors who previously did not sign an inventor Declaration, namely, Jae Hun Ku and Jae Hak Yee, have executed a Declaration for Patent Application. The executed Declaration is enclosed herewith. Accordingly, the Petition is moot. Please put copies of the executed Declaration for Patent Application in the file of the application, and please notify the undersigned that the matter is resolved.

EXPRESS MAIL LABEL NO:
EL 937 082 926 US

Respectfully submitted,

James E. Parsons
Attorney for Applicants
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